

# SF21 THRU SF28

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深圳FMS Kinter 131 6803 0058

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# SF21 THRU SF28

## 2.0A Axial Leaded Super Fast Rectifiers-50-600V

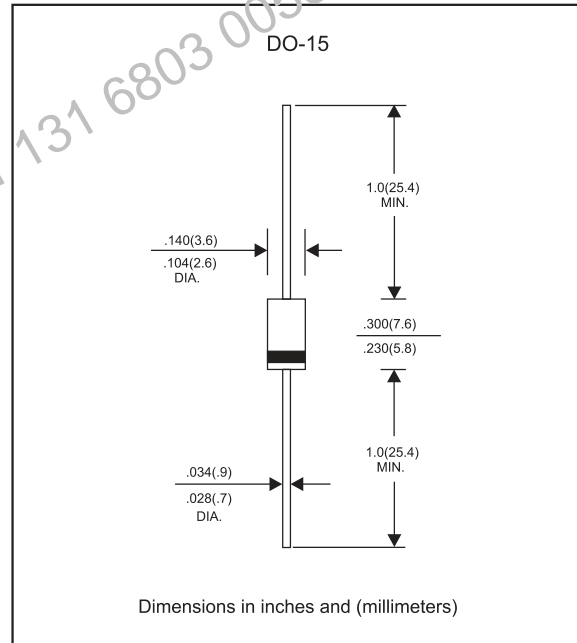
### Features

- Axial lead type devices for through hole design
- High current capability.
- Superfast recovery time for switching mode application.
- High surge current capability.
- Silicon rubber coating chip junction.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex SF21-H.

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-15
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 0.40 gram

### Package outline



### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = 55°C	I <sub>O</sub>			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I <sub>FSM</sub>			60	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 25°C	I <sub>R</sub>			5.0	μA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 100°C				150	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		60		pF
Storage temperature		T <sub>STG</sub>	-65		+175	°C

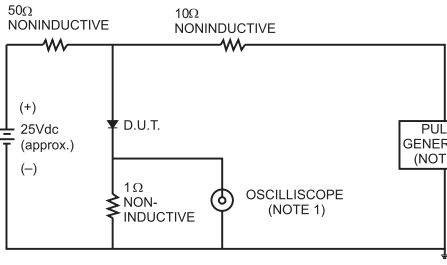
SYMBOLS	V <sub>RRM</sub> *1 (V)	V <sub>RMS</sub> *2 (V)	V <sub>R</sub> *3 (V)	V <sub>F</sub> *4 (V)	t <sub>rr</sub> *5 (ns)	Operating temperature T <sub>J</sub> , (°C)
SF21	50	35	50	0.95	35	-55 to +125
SF22	100	70	100			
SF23	150	105	150			
SF24	200	140	200			
SF25	300	210	300	1.25	35	-55 to +125
SF26	400	280	400			
SF27	500	350	500			
SF28	600	420	600	1.70	35	-55 to +125

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@I<sub>F</sub>=2.0A
- \*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

# Rating and characteristic curves (SF21 THRU SF28)

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

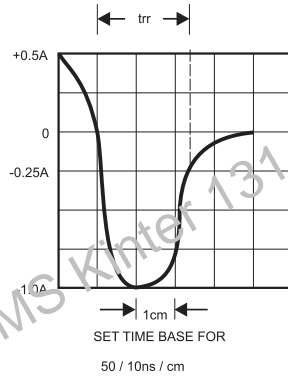


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

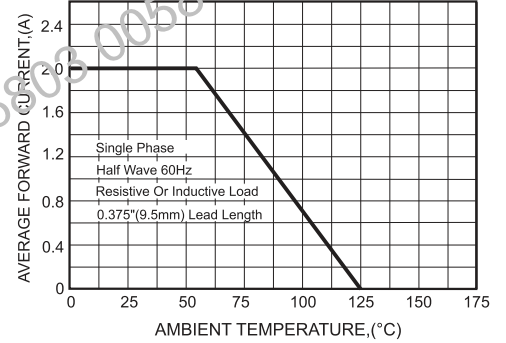


FIG.3-TYPICAL FORWARD CHARACTERISTICS

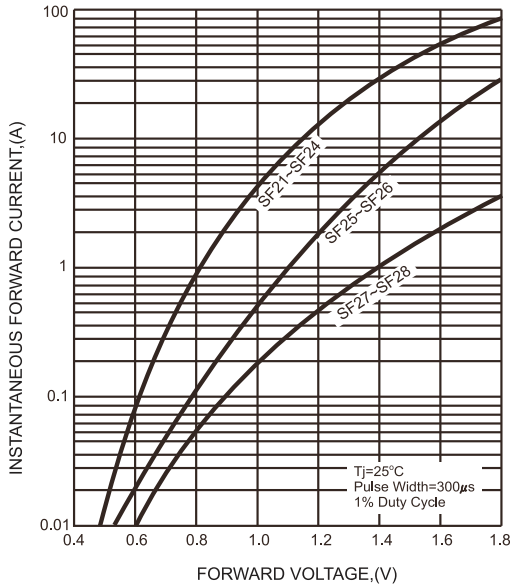


FIG.4-TYPICAL REVERSE CHARACTERISTICS

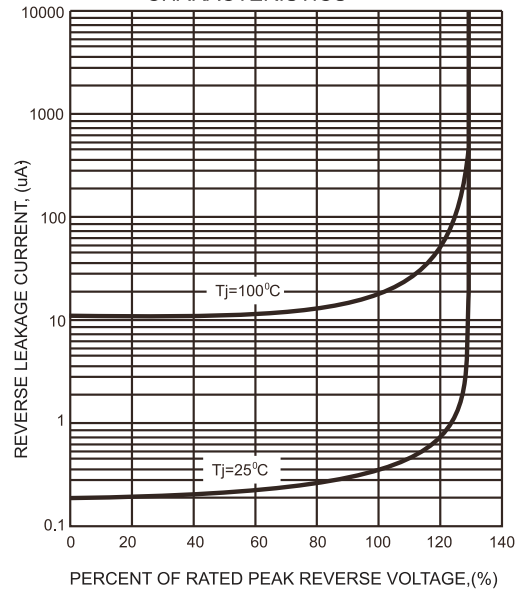


FIG.5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

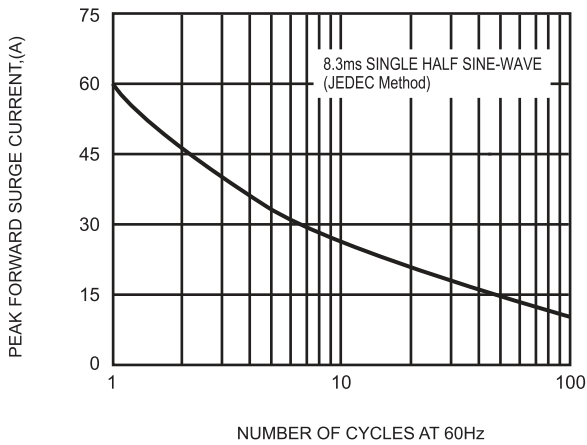
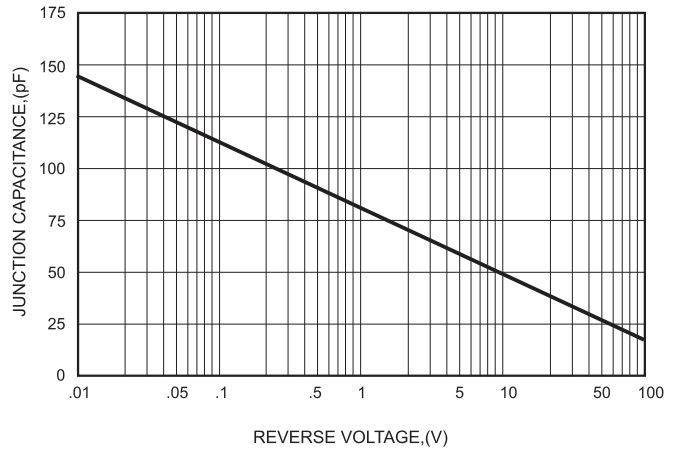




FIG.6-TYPICAL JUNCTION CAPACITANCE



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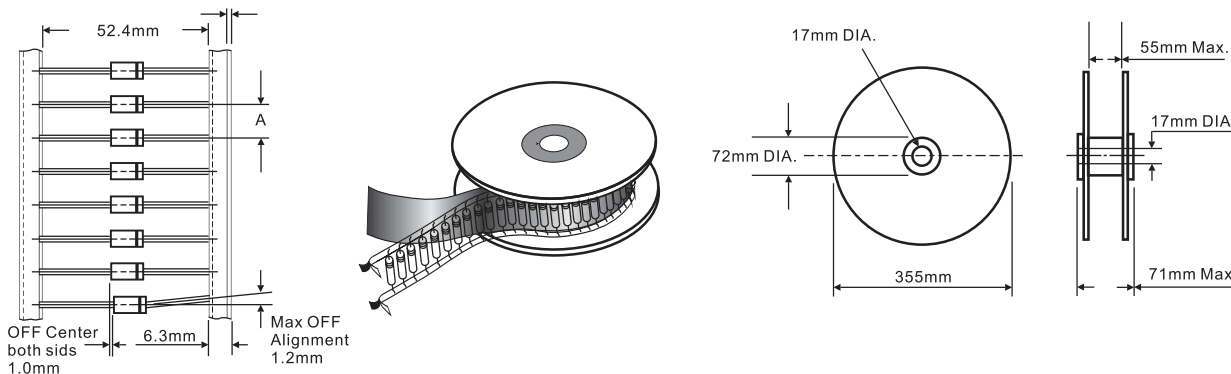
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
SF21	SF21
SF22	SF22
SF23	SF23
SF24	SF24
SF25	SF25
SF26	SF26
SF27	SF27
SF28	SF28

## Taping & bulk specifications for AXIAL devices



### REEL PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	4,000	5 mm	380 * 340 * 370	16,000	9.9

### AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	3,000	260 * 83 * 160	440 * 270 * 340	30,000	14.3

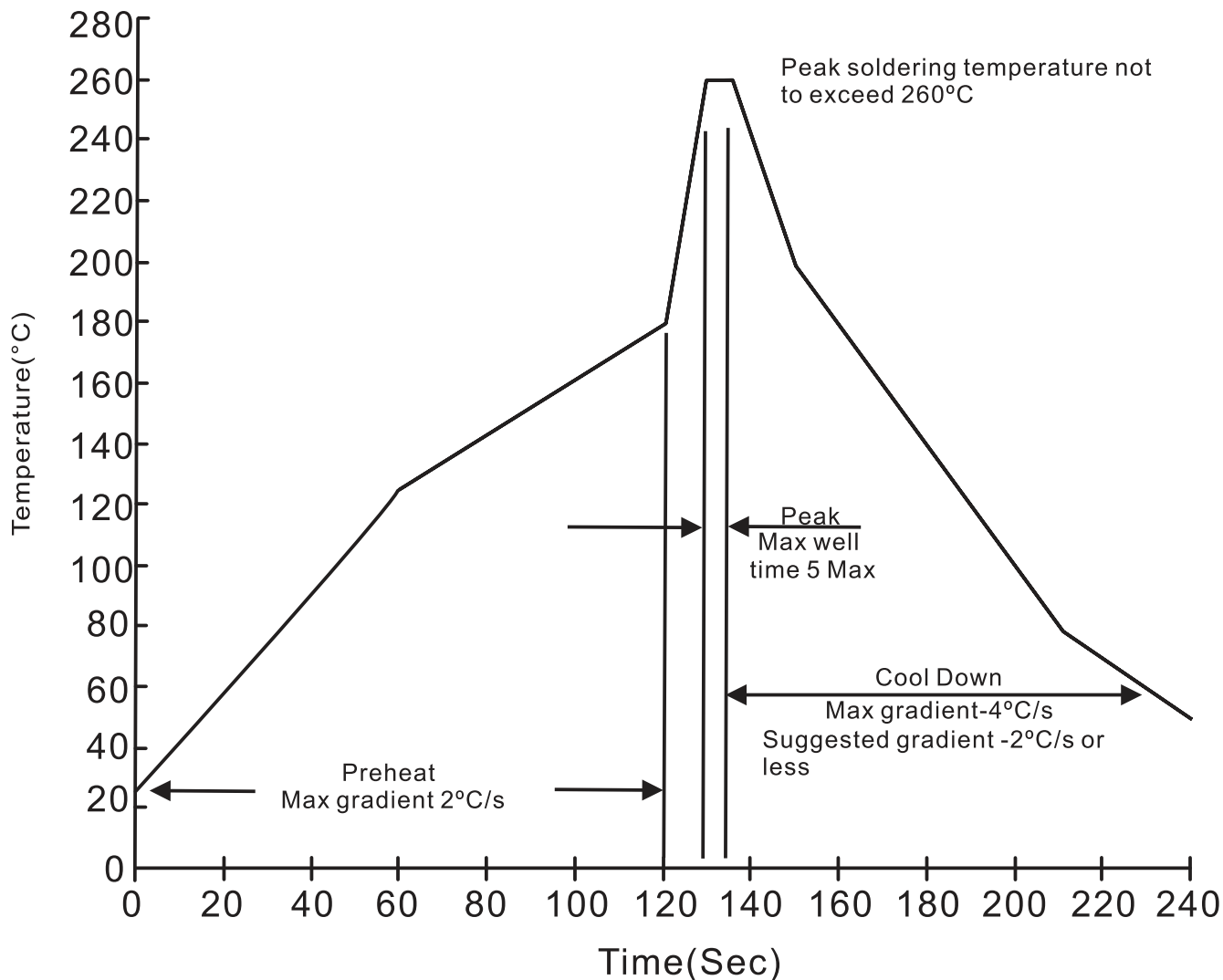
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BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	500	194 * 84 * 20	465 * 220 * 260	25,000	12.9

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



**SF21 THRU SF28****High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2$ sec. immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	1.0kg in axial lead direction for 10 sec. $I_F = I_O$	MIL-STD-202F METHOD-211A
4. Bend Lead	1.0kg weight applied to each lead bending arc $90^\circ \pm 5^\circ$ for 3 times, $I_F = I_O$	MIL-STD-202F METHOD-211A
5. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life	$T_A = 25^\circ\text{C}$ , $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1036
8. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	$-55^\circ\text{C}$ to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Thermal Shock	$0^\circ\text{C}$ for 5 min. rise to $100^\circ\text{C}$ for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
11. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
12. Humidity	at $T_A = 85^\circ\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
13. High Temperature Storage Life	at $175^\circ\text{C}$ for 1000 hrs.	MIL-STD-750D METHOD-1031